

## EAST Search History

| Ref # | Hits | Search Query   | DBs  | Default Operator | Plurals | Time Stamp       |
|-------|------|--|--|------------------|---------|------------------|
| L2    | 0    | (heat near sink) and (semiconductor or die or wafer or substrate) and (ground near lead) and package and encapsula\$6 and wire and leadframe and (257/687. ccls.)                    | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2006/05/19 09:40 |
| S1    | 26   | (heat near sink) and (semiconductor or die or wafer) and lead\$2 and electrical\$4 and ground and wire and encapsulant and polyimide   | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2006/05/18 14:58 |
| S2    | 24   | (heat near sink) and (semiconductor or die or wafer) and lead\$2 and electrical\$4 and ground and wire and encapsulant and polyimide and insulat\$4                                  | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2005/09/19 12:08 |
| S3    | 24   | (heat near sink) and (semiconductor or die or wafer) and lead\$2 and electrical\$4 and ground and wire and encapsulant and polyimide and insulat\$4 and plat\$4                      | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2005/09/19 12:09 |
| S4    | 24   | (heat near sink) and (semiconductor or die or wafer) and lead\$2 and electrical\$4 and ground and wire and encapsulant and polyimide and insulat\$4 and plat\$4 and package          | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2005/09/23 10:58 |
| S5    | 0    | (heat near sink) and (semiconductor or die or wafer) and lead\$2 and electrical\$4 and (ground near wire) and encapsula\$8 and polyimide and insulat\$4 and plat\$4 and package      | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2005/09/20 11:56 |
| S6    | 17   | (heat near sink) and (semiconductor or die or wafer) and lead\$2 and electrical\$4 and ground and wire and encapsulant and polyimide and insulat\$4 and plat\$4 and package and ring | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2005/09/23 10:58 |
| S7    | 0    | ((heat near sink) near4 (semiconductor or die or wafer)) and (plurality near4 lead\$2) and electrical\$4 and (ground near4 lead) and wire and encapsulant and polyimide              | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2006/03/28 14:45 |

## EAST Search History

|     |     |   |   |    |    |                  |
|-----|-----|---|---|----|----|------------------|
| S8  | 25  | ((heat near sink) near4 (semiconductor or die or wafer)) and (plurality near4 lead\$2) and electrical\$4 and (ground near4 lead) and wire and encapsulant     | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/03/28 14:46 |
| S9  | 0   | (heat near sink) and (semiconductor or die or wafer or substrate) and (ground near4 lead) and electrical\$4 and ground and wire and encapsulant and polyimide | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/05/18 14:59 |
| S10 | 709 | (heat near sink) and (semiconductor or die or wafer or substrate) and (ground near4 lead)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/05/18 15:00 |
| S11 | 209 | (heat near sink) and (semiconductor or die or wafer or substrate) and (ground near4 lead) and package and encapsula\$6  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/05/18 15:01 |
| S12 | 181 | (heat near sink) and (semiconductor or die or wafer or substrate) and (ground near4 lead) and package and encapsula\$6 and wire                               | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/05/18 15:04 |
| S13 | 48  | (heat near sink) and (semiconductor or die or wafer or substrate) and (ground near4 lead) and package and encapsula\$6 and wire and leadframe                 | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/05/18 15:05 |
| S14 | 31  | (heat near sink) and (semiconductor or die or wafer or substrate) and (ground near lead) and package and encapsula\$6 and wire and leadframe                  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/05/19 09:40 |